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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324j6tatr

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## **3 REGISTER & MEMORY MAP**

As shown in Figure 5, the MCU is capable of addressing 64K bytes of memories and I/O registers.

The available memory locations consist of 128 bytes of register locations, up to 1024 bytes of RAM and up to 32 Kbytes of user program memory. The RAM space includes up to 256 bytes for the stack from 0100h to 01FFh.

The highest address bytes contain the user reset and interrupt vectors.

**IMPORTANT:** Memory locations marked as "Reserved" must never be accessed. Accessing a reserved area can have unpredictable effects on the device.



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## FLASH PROGRAM MEMORY (Cont'd)

## 4.4 ICC Interface

ICC needs a minimum of 4 and up to 6 pins to be connected to the programming tool (see Figure 7). These pins are:

- RESET: device reset
- V<sub>SS</sub>: device power supply ground

## Figure 7. Typical ICC Interface

- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input/output serial data pin
- ICCSEL/V<sub>PP</sub>: programming voltage
- OSC1(or OSCIN): main clock input for external source (optional)
- V<sub>DD</sub>: application board power supply (optional, see Figure 7, Note 3)



#### Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the IC<u>C</u> session, the programming tool must control the RESET pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor<1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with R>1K or a reset management IC with open drain output and pull-up resistor>1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

3. The use of Pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 or OS-CIN pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multi-oscillator capability need to have OSC2 grounded in this case.



## INTERRUPTS (Cont'd)

## 7.7 EXTERNAL INTERRUPT CONTROL REGISTER (EICR)

#### Read/Write

Reset Value: 0000 0000 (00h)

7							0
IS11	IS10	IPB	IS21	IS20	IPA	0	0

Bit 7:6 = **IS1[1:0]** *ei2* and *ei3* sensitivity The interrupt sensitivity, defined using the IS1[1:0] bits, is applied to the following external interrupts: - ei2 (port B3..0)

1911	1910	External Interrupt Sensitivity						
1011	1010	IPB bit =0	IPB bit =1					
0	0	Falling edge & low level	Rising edge & high level					
0	1	Rising edge only	Falling edge only					
1	0	Falling edge only	Rising edge only					
1	1	Rising and falling edge						

- ei3 (port B4)

IS11	IS10	External Interrupt Sensitivity
0	0	Falling edge & low level
0	1	Rising edge only
1	0	Falling edge only
1	1	Rising and falling edge

These 2 bits can be written only when 11 and 10 of the CC register are both set to 1 (level 3).

## Bit 5 = **IPB** Interrupt polarity for port B

This bit is used to invert the sensitivity of the port B [3:0] external interrupts. It can be set and cleared by software only when I1 and I0 of the CC register are both set to 1 (level 3).

0: No sensitivity inversion

1: Sensitivity inversion

#### Bit 4:3 = **IS2[1:0]** *ei0* and *ei1* sensitivity The interrupt sensitivity, defined using the IS2[1:0] bits, is applied to the following external interrupts:

- ei0 (port A3..0)

1921	1630	External Interrupt Sensitivity						
1321	1320	IPA bit =0	IPA bit =1					
0	0	Falling edge & low level	Rising edge & high level					
0	1	Rising edge only	Falling edge only					
1	0	Falling edge only	Rising edge only					
1	1	Rising and falling edge						

- ei1 (port F2..0)

IS21	IS20	External Interrupt Sensitivity
0	0	Falling edge & low level
0	1	Rising edge only
1	0	Falling edge only
1	1	Rising and falling edge

These 2 bits can be written only when I1 and I0 of the CC register are both set to 1 (level 3).

## Bit 2 = IPA Interrupt polarity for port A

This bit is used to invert the sensitivity of the port A [3:0] external interrupts. It can be set and cleared by software only when I1 and I0 of the CC register are both set to 1 (level 3). 0: No sensitivity inversion

1: Sensitivity inversion

Bits 1:0 = Reserved, must always be kept cleared.



## 9 I/O PORTS

## 9.1 INTRODUCTION

The I/O ports offer different functional modes: – transfer of data through digital inputs and outputs

- and for specific pins:
- external interrupt generation
- alternate signal input/output for the on-chip peripherals.

An I/O port contains up to 8 pins. Each pin can be programmed independently as digital input (with or without interrupt generation) or digital output.

## 9.2 FUNCTIONAL DESCRIPTION

Each port has 2 main registers:

Data Register (DR)

- Data Direction Register (DDR)

and one optional register:

- Option Register (OR)

Each I/O pin may be programmed using the corresponding register bits in the DDR and OR registers: bit X corresponding to pin X of the port. The same correspondence is used for the DR register.

The following description takes into account the OR register, (for specific ports which do not provide this register refer to the I/O Port Implementation section). The generic I/O block diagram is shown in Figure 29

#### 9.2.1 Input Modes

The input configuration is selected by clearing the corresponding DDR register bit.

In this case, reading the DR register returns the digital value applied to the external I/O pin.

Different input modes can be selected by software through the OR register.

#### Notes:

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1. Writing the DR register modifies the latch value but does not affect the pin status.

2. When switching from input to output mode, the DR register has to be written first to drive the correct level on the pin as soon as the port is configured as an output.

3. Do not use read/modify/write instructions (BSET or BRES) to modify the DR register

#### External interrupt function

When an I/O is configured as Input with Interrupt, an event on this I/O can generate an external interrupt request to the CPU. Each pin can independently generate an interrupt request. The interrupt sensitivity is independently programmable using the sensitivity bits in the EICR register.

Each external interrupt vector is linked to a dedicated group of I/O port pins (see pinout description and interrupt section). If several input pins are selected simultaneously as interrupt sources, these are first detected according to the sensitivity bits in the EICR register and then logically ORed.

The external interrupts are hardware interrupts, which means that the request latch (not accessible directly by the application) is automatically cleared when the corresponding interrupt vector is fetched. To clear an unwanted pending interrupt by software, the sensitivity bits in the EICR register must be modified.

#### 9.2.2 Output Modes

The output configuration is selected by setting the corresponding DDR register bit. In this case, writing the DR register applies this digital value to the I/O pin through the latch. Then reading the DR register returns the previously stored value.

Two different output modes can be selected by software through the OR register: Output push-pull and open-drain.

DR register value and output pin status:

DR	Push-pull	Open-drain
0	V <sub>SS</sub>	Vss
1	V <sub>DD</sub>	Floating

#### 9.2.3 Alternate Functions

When an on-chip peripheral is configured to use a pin, the alternate function is automatically selected. This alternate function takes priority over the standard I/O programming.

When the signal is coming from an on-chip peripheral, the I/O pin is automatically configured in output mode (push-pull or open drain according to the peripheral).

When the signal is going to an on-chip peripheral, the I/O pin must be configured in input mode. In this case, the pin state is also digitally readable by addressing the DR register.

**Note**: Input pull-up configuration can cause unexpected value at the input of the alternate peripheral input. When an on-chip peripheral use a pin as input and output, this pin has to be configured in input floating mode.

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## 10.2 MAIN CLOCK CONTROLLER WITH REAL TIME CLOCK AND BEEPER (MCC/RTC)

The Main Clock Controller consists of three different functions:

- a programmable CPU clock prescaler
- a clock-out signal to supply external devices
- a real time clock timer with interrupt capability

Each function can be used independently and simultaneously.

#### 10.2.1 Programmable CPU Clock Prescaler

The programmable CPU clock prescaler supplies the clock for the ST7 CPU and its internal peripherals. It manages SLOW power saving mode (See Section 8.2 SLOW MODE for more details).

The prescaler selects the  $f_{CPU}$  main clock frequency and is controlled by three bits in the MCCSR register: CP[1:0] and SMS.

#### 10.2.2 Clock-out Capability

The clock-out capability is an alternate function of an I/O port pin that outputs the  $f_{CPU}$  clock to drive

external devices. It is controlled by the MCO bit in the MCCSR register.

**CAUTION**: When selected, the clock out pin suspends the clock during ACTIVE-HALT mode.

## 10.2.3 Real Time Clock Timer (RTC)

The counter of the real time clock timer allows an interrupt to be generated based on an accurate real time clock. Four different time bases depending directly on  $f_{OSC2}$  are available. The whole functionality is controlled by four bits of the MCC-SR register: TB[1:0], OIE and OIF.

When the RTC interrupt is enabled (OIE bit set), the ST7 enters ACTIVE-HALT mode when the HALT instruction is executed. See Section 8.4 AC-TIVE-HALT AND HALT MODES for more details.

#### 10.2.4 Beeper

The beep function is controlled by the MCCBCR register. It can output three selectable frequencies on the BEEP pin (I/O port alternate function).

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#### Figure 34. Main Clock Controller (MCC/RTC) Block Diagram



## **10.3 16-BIT TIMER**

## 10.3.1 Introduction

The timer consists of a 16-bit free-running counter driven by a programmable prescaler.

It may be used for a variety of purposes, including pulse length measurement of up to two input signals (*input capture*) or generation of up to two output waveforms (*output compare* and *PWM*).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the CPU clock prescaler.

Some ST7 devices have two on-chip 16-bit timers. They are completely independent, and do not share any resources. They are synchronized after a MCU reset as long as the timer clock frequencies are not modified.

This description covers one or two 16-bit timers. In ST7 devices with two timers, register names are prefixed with TA (Timer A) or TB (Timer B).

#### 10.3.2 Main Features

- Programmable prescaler: f<sub>CPU</sub> divided by 2, 4 or 8.
- Overflow status flag and maskable interrupt
- External clock input (must be at least 4 times slower than the CPU clock speed) with the choice of active edge
- 1 or 2 Output Compare functions each with:
  - 2 dedicated 16-bit registers
  - 2 dedicated programmable signals
  - 2 dedicated status flags
  - 1 dedicated maskable interrupt
- 1 or 2 Input Capture functions each with:
  - 2 dedicated 16-bit registers
  - 2 dedicated active edge selection signals
  - 2 dedicated status flags
  - 1 dedicated maskable interrupt
- Pulse width modulation mode (PWM)
- One pulse mode
- Reduced Power Mode
- 5 alternate functions on I/O ports (ICAP1, ICAP2, OCMP1, OCMP2, EXTCLK)\*

The Block Diagram is shown in Figure 35.

\*Note: Some timer pins may not be available (not bonded) in some ST7 devices. Refer to the device pin out description.

When reading an input signal on a non-bonded pin, the value will always be '1'.

#### **10.3.3 Functional Description**

#### 10.3.3.1 Counter

The main block of the Programmable Timer is a 16-bit free running upcounter and its associated 16-bit registers. The 16-bit registers are made up of two 8-bit registers called high & low.

Counter Register (CR):

- Counter High Register (CHR) is the most significant byte (MS Byte).
- Counter Low Register (CLR) is the least significant byte (LS Byte).

Alternate Counter Register (ACR)

- Alternate Counter High Register (ACHR) is the most significant byte (MS Byte).
- Alternate Counter Low Register (ACLR) is the least significant byte (LS Byte).

These two read-only 16-bit registers contain the same value but with the difference that reading the ACLR register does not clear the TOF bit (Timer overflow flag), located in the Status register, (SR), (see note at the end of paragraph titled 16-bit read sequence).

Writing in the CLR register or ACLR register resets the free running counter to the FFFCh value.

Both counters have a reset value of FFFCh (this is the only value which is reloaded in the 16-bit timer). The reset value of both counters is also FFFCh in One Pulse mode and PWM mode.

The timer clock depends on the clock control bits of the CR2 register, as illustrated in Table 16 Clock Control Bits. The value in the counter register repeats every 131072, 262144 or 524288 CPU clock cycles depending on the CC[1:0] bits.

The timer frequency can be  $f_{CPU}/2$ ,  $f_{CPU}/4$ ,  $f_{CPU}/8$  or an external frequency.

**Caution:** In Flash devices, Timer A functionality has the following restrictions:

- TAOC2HR and TAOC2LR registers are write only
- Input Capture 2 is not implemented
- The corresponding interrupts cannot be used (ICF2, OCF2 forced by hardware to zero)

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## SERIAL PERIPHERAL INTERFACE (Cont'd)

- SS: Slave select:

This input signal acts as a 'chip select' to let the SPI master communicate with slaves individually and to avoid contention on the data lines. Slave SS inputs can be driven by standard I/O ports on the master MCU.

#### 10.4.3.1 Functional Description

A basic example of interconnections between a single master and a single slave is illustrated in Figure 47.

The MOSI pins are connected together and the MISO pins are connected together. In this way data is transferred serially between master and slave (most significant bit first).

The communication is always initiated by the master. When the master device transmits data to a slave device via MOSI pin, the slave device responds by sending data to the master device via the MISO pin. This implies full duplex communication with both data out and data in synchronized with the same clock signal (which is provided by the master device via the SCK pin).

To use a single data line, the MISO and MOSI pins must be connected at each node (in this case only simplex communication is possible).

Four possible data/clock timing relationships may be chosen (see Figure 50) but master and slave must be programmed with the same timing mode.



#### Figure 47. Single Master/ Single Slave Application

## **10.5 SERIAL COMMUNICATIONS INTERFACE (SCI)**

## 10.5.1 Introduction

The Serial Communications Interface (SCI) offers a flexible means of full-duplex data exchange with external equipment requiring an industry standard NRZ asynchronous serial data format. The SCI offers a very wide range of baud rates using two baud rate generator systems.

## 10.5.2 Main Features

- Full duplex, asynchronous communications
- NRZ standard format (Mark/Space)
- Dual baud rate generator systems
- Independently programmable transmit and receive baud rates up to 500K baud
- Programmable data word length (8 or 9 bits)
- Receive buffer full, Transmit buffer empty and End of Transmission flags
- Two receiver wake-up modes:
  - Address bit (MSB)
  - Idle line
- Muting function for multiprocessor configurations
- Separate enable bits for Transmitter and Receiver
- Four error detection flags:
  - Overrun error
  - Noise error
  - Frame error
  - Parity error
- Five interrupt sources with flags:
  - Transmit data register empty
  - Transmission complete
  - Receive data register full
  - Idle line received
  - Overrun error detected
- Parity control:
  - Transmits parity bit
  - Checks parity of received data byte
- Reduced power consumption mode

#### **10.5.3 General Description**

The interface is externally connected to another device by two pins (see Figure 2.):

- TDO: Transmit Data Output. When the transmitter and the receiver are disabled, the output pin returns to its I/O port configuration. When the transmitter and/or the receiver are enabled and nothing is to be transmitted, the TDO pin is at high level.
- RDI: Receive Data Input is the serial data input. Oversampling techniques are used for data recovery by discriminating between valid incoming data and noise.

Through these pins, serial data is transmitted and received as frames comprising:

- An Idle Line prior to transmission or reception
- A start bit
- A data word (8 or 9 bits) least significant bit first
- A Stop bit indicating that the frame is complete
- This interface uses two types of baud rate generator:
- A conventional type for commonly-used baud rates
- An extended type with a prescaler offering a very wide range of baud rates even with non-standard oscillator frequencies



## SERIAL COMMUNICATIONS INTERFACE (Cont'd)

## 10.5.4.2 Transmitter

The transmitter can send data words of either 8 or 9 bits depending on the M bit status. When the M bit is set, word length is 9 bits and the 9th bit (the MSB) has to be stored in the T8 bit in the SCICR1 register.

#### **Character Transmission**

During an SCI transmission, data shifts out least significant bit first on the TDO pin. In this mode, the SCIDR register consists of a buffer (TDR) between the internal bus and the transmit shift register (see Figure 1.).

#### Procedure

- Select the M bit to define the word length.
- Select the desired baud rate using the SCIBRR and the SCIETPR registers.
- Set the TE bit to assign the TDO pin to the alternate function and to send a idle frame as first transmission.
- Access the SCISR register and write the data to send in the SCIDR register (this sequence clears the TDRE bit). Repeat this sequence for each data to be transmitted.

Clearing the TDRE bit is always performed by the following software sequence:

- 1. An access to the SCISR register
- 2. A write to the SCIDR register

The TDRE bit is set by hardware and it indicates:

- The TDR register is empty.

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- The data transfer is beginning.
- The next data can be written in the SCIDR register without overwriting the previous data.

This flag generates an interrupt if the TIE bit is set and the I bit is cleared in the CCR register.

When a transmission is taking place, a write instruction to the SCIDR register stores the data in the TDR register and which is copied in the shift register at the end of the current transmission.

When no transmission is taking place, a write instruction to the SCIDR register places the data directly in the shift register, the data transmission starts, and the TDRE bit is immediately set. When a frame transmission is complete (after the stop bit) the TC bit is set and an interrupt is generated if the TCIE is set and the I bit is cleared in the CCR register.

Clearing the TC bit is performed by the following software sequence:

- 1. An access to the SCISR register
- 2. A write to the SCIDR register

**Note:** The TDRE and TC bits are cleared by the same software sequence.

#### **Break Characters**

Setting the SBK bit loads the shift register with a break character. The break frame length depends on the M bit (see Figure 2.).

As long as the SBK bit is set, the SCI send break frames to the TDO pin. After clearing this bit by software the SCI insert a logic 1 bit at the end of the last break frame to guarantee the recognition of the start bit of the next frame.

#### Idle Characters

Setting the TE bit drives the SCI to send an idle frame before the first data frame.

Clearing and then setting the TE bit during a transmission sends an idle frame after the current word.

**Note:** Resetting and setting the TE bit causes the data in the TDR register to be lost. Therefore the best time to toggle the TE bit is when the TDRE bit is set, that is, before writing the next byte in the SCIDR.

## SERIAL COMMUNICATIONS INTERFACE (Cont'd)

## **Framing Error**

A framing error is detected when:

- The stop bit is not recognized on reception at the expected time, following either a de-synchronization or excessive noise.
- A break is received.

When the framing error is detected:

- the FE bit is set by hardware
- Data is transferred from the Shift register to the SCIDR register.
- No interrupt is generated. However this bit rises at the same time as the RDRF bit which itself generates an interrupt.

The FE bit is reset by a SCISR register read operation followed by a SCIDR register read operation.

## 10.5.4.4 Conventional Baud Rate Generation

The baud rate for the receiver and transmitter (Rx and Tx) are set independently and calculated as follows:

$$Tx = \frac{f_{CPU}}{(16*PR)*TR} \qquad Rx = \frac{f_{CPU}}{(16*PR)*RR}$$

with:

PR = 1, 3, 4 or 13 (see SCP[1:0] bits) TR = 1, 2, 4, 8, 16, 32, 64,128 (see SCT[2:0] bits) RR = 1, 2, 4, 8, 16, 32, 64,128 (see SCR[2:0] bits)

All these bits are in the SCIBRR register.

**Example:** If  $f_{CPU}$  is 8 MHz (normal mode) and if PR = 13 and TR = RR = 1, the transmit and receive baud rates are 38400 baud.

**Note:** The baud rate registers MUST NOT be changed while the transmitter or the receiver is enabled.

## 10.5.4.5 Extended Baud Rate Generation

The extended prescaler option gives a very fine tuning on the baud rate, using a 255 value prescaler, whereas the conventional Baud Rate Generator retains industry standard software compatibility.

The extended baud rate generator block diagram is described in the Figure 3.

The output clock rate sent to the transmitter or to the receiver is the output from the 16 divider divided by a factor ranging from 1 to 255 set in the SCI-ERPR or the SCIETPR register. **Note:** the extended prescaler is activated by setting the SCIETPR or SCIERPR register to a value other than zero. The baud rates are calculated as follows:

$$Tx = \frac{f_{CPU}}{16 \cdot ETPR^{*}(PR^{*}TR)} Rx = \frac{f_{CPU}}{16 \cdot ERPR^{*}(PR^{*}RR)}$$

with:

ETPR = 1,..,255 (see SCIETPR register)

ERPR = 1,.. 255 (see SCIERPR register)

## 10.5.4.6 Receiver Muting and Wake-up Feature

In multiprocessor configurations it is often desirable that only the intended message recipient should actively receive the full message contents, thus reducing redundant SCI service overhead for all non addressed receivers.

The non addressed devices may be placed in sleep mode by means of the muting function.

Setting the RWU bit by software puts the SCI in sleep mode:

All the reception status bits can not be set.

All the receive interrupts are inhibited.

A muted receiver may be awakened by one of the following two ways:

- by Idle Line detection if the WAKE bit is reset,

- by Address Mark detection if the WAKE bit is set.

Receiver wakes-up by Idle Line detection when the Receive line has recognized an Idle Frame. Then the RWU bit is reset by hardware but the IDLE bit is not set.

Receiver wakes-up by Address Mark detection when it received a "1" as the most significant bit of a word, thus indicating that the message is an address. The reception of this particular word wakes up the receiver, resets the RWU bit and sets the RDRF bit, which allows the receiver to receive this word normally and to use it as an address word.

**CAUTION**: In Mute mode, do not write to the SCICR2 register. If the SCI is in Mute mode during the read operation (RWU = 1) and a address mark wake up event occurs (RWU is reset) before the write operation, the RWU bit is set again by this write operation. Consequently the address byte is lost and the SCI is not woken up from Mute mode.



## SERIAL COMMUNICATIONS INTERFACE (Cont'd) EXTENDED RECEIVE PRESCALER DIVISION REGISTER (SCIERPR)

#### Read/Write

Reset Value: 0000 0000 (00h)

Allows setting of the Extended Prescaler rate division factor for the receive circuit.

7							0
ERPR							
7	6	5	4	3	2	1	0

# Bits 7:0 = **ERPR[7:0]** 8-bit Extended Receive Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see Figure 3.) is divided by the binary factor set in the SCIERPR register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

# Table 21. Baudrate Selection

# EXTENDED TRANSMIT PRESCALER DIVISION REGISTER (SCIETPR)

## Read/Write

Reset Value:0000 0000 (00h)

Allows setting of the External Prescaler rate division factor for the transmit circuit.

7							0
ETPR							
7	6	5	4	3	2	1	0

# Bits 7:0 = **ETPR[7:0]** 8-bit Extended Transmit Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see Figure 3.) is divided by the binary factor set in the SCIETPR register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

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			Cor		Baud		
Symbol	Parameter	f <sub>CPU</sub>	Accuracy vs Standard	Prescaler	Standard	Rate	Unit
f <sub>Tx</sub> f <sub>Rx</sub>	Communication frequency	8 MHz	~0.16%	Conventional Mode TR (or RR)=128, PR=13 TR (or RR)= 32, PR=13 TR (or RR)= 16, PR=13 TR (or RR)= 8, PR=13 TR (or RR)= 4, PR=13 TR (or RR)= 16, PR= 3 TR (or RR)= 2, PR=13 TR (or RR)= 1, PR=13	300 1200 2400 4800 9600 10400 19200 38400	~300.48 ~1201.92 ~2403.84 ~4807.69 ~9615.38 ~10416.67 ~19230.77 ~38461.54	Hz
			~0.79%	Extended Mode ETPR (or ERPR) = 35, TR (or RR)= 1, PR=1	14400	~14285.71	

## INSTRUCTION SET OVERVIEW (Cont'd)

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Mnemo	Description	Function/Example	Dst	Src	ſ	11	Н	10	Ν	Ζ	С
JRULE	Jump if $(C + Z = 1)$	Unsigned <=			Ī						
LD	Load	dst <= src	reg, M	M, reg					Ν	Ζ	
MUL	Multiply	X,A = X * A	A, X, Y	X, Y, A	Ī		0				0
NEG	Negate (2's compl)	neg \$10	reg, M		Ī				Ν	Ζ	С
NOP	No Operation				Ī						
OR	OR operation	A = A + M	А	М	Ī				Ν	Ζ	
DOD	Don from the Steel	pop reg	reg	М	Ī						
POP	Pop from the Stack	pop CC	CC	М	Ī	11	Н	10	Ν	Ζ	С
PUSH	Push onto the Stack	push Y	М	reg, CC	Ī						
RCF	Reset carry flag	C = 0									0
RET	Subroutine Return				Ē						
RIM	Enable Interrupts	11:0 = 10 (level 0)				1		0			
RLC	Rotate left true C	C <= A <= C	reg, M		Ē				Ν	Ζ	С
RRC	Rotate right true C	C => A => C	reg, M		Ē				Ν	Ζ	С
RSP	Reset Stack Pointer	S = Max allowed									
SBC	Substract with Carry	A = A - M - C	А	М					Ν	Ζ	С
SCF	Set carry flag	C = 1									1
SIM	Disable Interrupts	11:0 = 11 (level 3)				1		1			
SLA	Shift left Arithmetic	C <= A <= 0	reg, M		Ī				Ν	Ζ	С
SLL	Shift left Logic	C <= A <= 0	reg, M		Ī				Ν	Ζ	С
SRL	Shift right Logic	0 => A => C	reg, M		Ī				0	Ζ	С
SRA	Shift right Arithmetic	A7 => A => C	reg, M		Ī				Ν	Ζ	С
SUB	Substraction	A = A - M	А	М					Ν	Ζ	С
SWAP	SWAP nibbles	A7-A4 <=> A3-A0	reg, M						Ν	Ζ	
TNZ	Test for Neg & Zero	tnz lbl1			Ē				Ν	Ζ	
TRAP	S/W trap	S/W interrupt				1		1			
WFI	Wait for Interrupt				ľ	1		0			
XOR	Exclusive OR	A = A XOR M	А	М					Ν	Z	

## **OPERATING CONDITIONS** (Cont'd)

## **12.4 LVD/AVD CHARACTERISTICS**

## 12.4.1 Operating Conditions with Low Voltage Detector (LVD)

Subject to general operating conditions for  $\mathsf{T}_\mathsf{A}$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	Design and a set of the set of the set of the	VD level = High in option byte	4.0 <sup>1)</sup>	4.2	4.5	
V <sub>IT+(LVD)</sub>	Reset release threshold	VD level = Med. in option byte <sup>2)</sup>	3.55 <sup>1)</sup>	3.75	4.0 <sup>1)</sup>	
		VD level = Low in option byte <sup>2)</sup>	2.95 <sup>1)</sup>	3.15	3.35 <sup>1)</sup>	v
	Design and the should be	VD level = High in option byte	3.8	4.0	4.25 <sup>1)</sup>	v
V <sub>IT-(LVD)</sub>	(V <sub>DD</sub> fall)	VD level = Med. in option byte <sup>2)</sup>	3.35 <sup>1)</sup>	3.55	3.75 <sup>1)</sup>	
		VD level = Low in option byte <sup>2)</sup>	2.8 <sup>1)</sup>	3.0	3.15 <sup>1)</sup>	
V <sub>hys(LVD)</sub>	LVD voltage threshold hysteresis 1)	V <sub>IT+(LVD)</sub> -V <sub>IT-(LVD)</sub>	150	200	250	mV
Vt <sub>POR</sub>	V <sub>DD</sub> rise time <sup>1)</sup>		6μs/V		100ms/V	
t <sub>g(VDD)</sub>	Filtered glitch delay on $V_{DD}^{1)}$	Not detected by the LVD			40	ns

#### Notes:

1. Data based on characterization results, not tested in production.

2. If the medium or low thresholds are selected, the detection may occur outside the specified operating voltage range.

## 12.4.2 Auxiliary Voltage Detector (AVD) Thresholds

Subject to general operating conditions for  $\mathsf{T}_\mathsf{A}$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	$1 \rightarrow 0$ AV/DE flog toggle threshold	VD level = High in option byte	4.4 <sup>1)</sup>	4.6	4.9	
V <sub>IT+(AVD)</sub>	$I \Rightarrow 0 \text{ AVDF flag toggle threshold}$	VD level = Med. in option byte	3.95 <sup>1)</sup>	4.15	4.4 <sup>1)</sup>	
· · ·	(VDD lise)	VD level = Low in option byte	3.4 <sup>1)</sup>	3.6	3.8 <sup>1)</sup>	v
V <sub>IT-(AVD)</sub>	$0 \rightarrow 1$ AVDE flog toggle threshold	VD level = High in option byte	4.2	4.4	4.65 <sup>1)</sup>	v
	(V <sub>DD</sub> fall)	VD level = Med. in option byte	3.75 <sup>1)</sup>	4.0	4.2 <sup>1)</sup>	
		VD level = Low in option byte	3.2 <sup>1)</sup>	3.4	3.6 <sup>1)</sup>	
V <sub>hys(AVD)</sub>	AVD voltage threshold hysteresis	V <sub>IT+(AVD)</sub> -V <sub>IT-(AVD)</sub>		200		mV
$\Delta V_{IT}$	Voltage drop between AVD flag set and LVD reset activated	V <sub>IT-(AVD)</sub> -V <sub>IT-(LVD)</sub>		450		mV

1. Data based on characterization results not tested in production.

## SUPPLY CURRENT CHARACTERISTICS (Cont'd)

## 12.5.1.1 Power Consumption vs f<sub>CPU</sub>: Flash Devices

## Figure 61. Typical $I_{DD}$ in RUN mode



## Figure 62. Typical I<sub>DD</sub> in SLOW mode

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## Figure 63. Typical I<sub>DD</sub> in WAIT mode



Figure 64. Typ.  $I_{DD}$  in SLOW-WAIT mode



## CLOCK CHARACTERISTICS (Cont'd)

## **12.6.5 PLL Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f <sub>OSC</sub>	PLL input frequency range		2		4	MHz
$\Delta f_{CPU} / f_{CPU}$	Instantaneous PLL iitter <sup>1</sup> )	Flash ST72F324, f <sub>OSC</sub> = 4 MHz.		1.0	2.5	0/
		Flash ST72F324, f <sub>OSC</sub> = 2 MHz.		2.5	4.0	70

#### Note:

1. Data characterized but not tested.

The user must take the PLL jitter into account in the application (for example in serial communication or sampling of high frequency signals). The PLL jitter is a periodic effect, which is integrated over several CPU cycles. Therefore the longer the period of the application signal, the less it will be impacted by the PLL jitter.

Figure 68 shows the PLL jitter integrated on application signals in the range 125kHz to 2MHz. At frequencies of less than 125KHz, the jitter is negligible.

#### Figure 68. Integrated PLL Jitter vs signal frequency<sup>1</sup>



Note 1: Measurement conditions: f<sub>CPU</sub> = 8MHz.



## **12.8 EMC CHARACTERISTICS**

Susceptibility tests are performed on a sample basis during product characterization.

# 12.8.1 Functional EMS (Electro Magnetic Susceptibility)

Based on a simple running application on the product (toggling 2 LEDs through I/O ports), the product is stressed by two electro magnetic events until a failure occurs (indicated by the LEDs).

- ESD: Electro-Static Discharge (positive and negative) is applied on all pins of the device until a functional disturbance occurs. This test conforms with the IEC 1000-4-2 standard.
- FTB: A Burst of Fast Transient voltage (positive and negative) is applied to V<sub>DD</sub> and V<sub>SS</sub> through a 100pF capacitor, until a functional disturbance occurs. This test conforms with the IEC 1000-4-4 standard.

A device reset allows normal operations to be resumed. The test results are given in the table below based on the EMS levels and classes defined in application note AN1709.

# 12.8.1.1 Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

#### Software recommendations:

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

#### Prequalification trials:

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the RE-SET pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behaviour is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015)

Symbol	Parameter	Conditions	Level/ Class
V <sub>FESD</sub>	Voltage limits to be applied on any I/O pin to induce a functional disturbance	8 or 16K Flash device, $V_{DD}$ =5V, T <sub>A</sub> =+25°C, f <sub>OSC</sub> =8MHz conforms to IEC 1000-4-2	4B
V <sub>FFTB</sub>	Fast transient voltage burst limits to be applied through 100pF on $V_{DD}$ and $V_{DD}$ pins to induce a functional disturbance	V <sub>DD</sub> =5V, T <sub>A</sub> =+25°C, f <sub>OSC</sub> =8MHz conforms to IEC 1000-4-4	4A

## CONTROL PIN CHARACTERISTICS (Cont'd)



## Figure 77. RESET pin protection when LVD is enabled.<sup>1)2)3)4)5)6)7)</sup>





1. The reset network protects the device against parasitic resets.

2. The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).

3. Whatever the reset source is (internal or external), the user must ensure that the level on the  $\overline{\text{RESET}}$  pin can go below the V<sub>IL</sub> max. level specified in Section 12.10.1. Otherwise the reset will not be taken into account internally.

4. Because the reset circuit is <u>design</u>ed to allow the internal RESET to be output in the RESET pin, the user must ensure that the current sunk on the RESET pin (by an external pull-up for example) is less than the absolute maximum value specified for  $I_{INJ(RESET)}$  in Section 12.2.2 on page 117.

5. When the LVD is enabled, it is mandatory not to connect a pull-up resistor. A 10nF pull-down capacitor is recommended to filter noise on the reset line.

6. In case a capacitive power supply is used, it is recommended to connect a1M $\Omega$  pull-down resistor to the RESET pin to discharge any residual voltage induced by this capacitive power supply (this will add 5µA to the power consumption of the MCU).

7. Tips when using the LVD:

- 1. Check that all recommendations related to ICCCLK and reset circuit have been applied (see notes above)
- 2. Check that the power supply is properly decoupled (100nF + 10 $\mu$ F close to the MCU). Refer to AN1709. If this cannot be done, it is recommended to put a 100nF + 1M $\Omega$  pull-down on the RESET pin.
- 3. The capacitors connected on the RESET pin and also the power supply are key to avoiding any start-up marginality. In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: replace 10nF pull-down on the RESET pin with a 5µF to 20µF capacitor."

## 10-BIT ADC CHARACTERISTICS (Cont'd)

## 12.13.3 ADC Accuracy

Conditions:  $V_{DD}=5V^{(1)}$ 

Symbol	Parameter	Conditions	Flash I	Unit	
	Faidilietei	Conditions	Тур	Max <sup>2)</sup>	onit
IE <sub>T</sub> I	Total unadjusted error 1)		4	6	
IE <sub>O</sub> I	Offset error 1)		3	5	
IE <sub>G</sub> I	Gain Error <sup>1)</sup>		0.5	4.5	I SB
IE <sub>D</sub> I	Differential linearity error	CPU in run mode @ f <sub>ADC</sub> 2 MHz.	1.5	4.5	
IELI	Integral linearity error 1)	CPU in run mode @ f <sub>ADC</sub> 2 MHz.	1.5	4.5	

#### Notes:

1. ADC Accuracy vs. Negative Injection Current: Injecting negative current may reduce the accuracy of the conversion being performed on another analog input.

Any positive injection current within the limits specified for  $I_{INJ(PIN)}$  and  $\Sigma I_{INJ(PIN)}$  in Section 12.9 does not affect the ADC accuracy.

2. Data based on characterization results, monitored in production to guarantee 99.73% within  $\pm$  max value from -40°C to 125°C ( $\pm$  3 $\sigma$  distribution limits).

## Figure 87. ADC Accuracy Characteristics



## 14 ST72324 DEVICE CONFIGURATION AND ORDERING INFORMATION

## **14.1 FLASH OPTION BYTES**

	STATIC OPTION BYTE 0							STATIC OPTION BYTE 1								
	7						0	7					0			
	WD		rved	VD	rved	а_ 15	2	OSCTYPE		OSCRANGE			OFF			
	НАLТ	SW	Rese	1	0	Rese	Rese	FMF	PK	.SH	1	0	2	1	0	PLL0
Default	1	1	1	0	0	1	1	1	1	1	1	0	1	1	1	1

The option bytes allows the hardware configuration of the microcontroller to be selected. They have no address in the memory map and can be accessed only in programming mode (for example using a standard ST7 programming tool). The default content of the FLASH is fixed to FFh. To program directly the FLASH devices using ICP, FLASH devices are shipped to customers with the internal RC clock source.

## **OPTION BYTE 0**

OPT7= **WDG HALT** Watchdog reset on HALT This option bit determines if a RESET is generated when entering HALT mode while the Watchdog is active.

0: No Reset generation when entering Halt mode 1: Reset generation when entering Halt mode

OPT6= **WDG SW** Hardware or software watchdog This option bit selects the watchdog type.

0: Hardware (watchdog always enabled)

1: Software (watchdog to be enabled by software)

OPT5 = Reserved, must be kept at default value.

## OPT4:3= VD[1:0] Voltage detection

These option bits enable the voltage detection block (LVD, and AVD) with a selected threshold for the LVD and AVD.

Selected Low Voltage Detector	VD1	VD0
LVD and AVD Off	1	1
Lowest Voltage Threshold (V <sub>DD</sub> ~3V)	1	0
Medium Voltage Threshold (V <sub>DD</sub> ~3.5V)	0	1
Highest Voltage Threshold (V <sub>DD</sub> ~4V)	0	0

**Caution:** If the medium or low thresholds are selected, the detection may occur outside the specified operating voltage range. Below 3.8V, device operation is not guaranteed. For details on the AVD and LVD threshold levels refer to Section 12.4.1 on page 119

OPT2:1 = Reserved, must be kept at default value.

OPT0= **FMP\_R** Flash memory read-out protection Read-out protection, when selected, provides a protection against Program Memory content extraction and against write access to Flash memory.

Erasing the option bytes when the FMP\_R option is selected causes the whole user memory to be erased first, and the device can be reprogrammed. Refer to Section 7.3.1 on page 37 and the ST7 Flash Programming Reference Manual for more details.

0: Read-out protection enabled

1: Read-out protection disabled



## 14.4 DEVELOPMENT TOOLS

STMicroelectronics offers a range of hardware and software development tools for the ST7 microcontroller family. Full details of tools available for the ST7 from third party manufacturers can be obtain from the STMicroelectronics Internet site: → http://:mcu.st.com.

Tools from these manufacturers include C compliers, emulators and gang programmers.

## Emulators

Two types of emulators are available from ST for the ST72324 family:

- ST7 DVP3 entry-level emulator offers a flexible and modular debugging and programming solution. SDIP42 & SDIP32 probes/adapters are included, other packages need a specific connection kit (refer to Table 28)
- ST7 EMU3 high-end emulator is delivered with everything (probes, TEB, adapters etc.) needed to start emulating the ST72324 family. To configure it to emulate other ST7 subfamily devices, the active probe for the ST7EMU3 can be changed and the ST7EMU3 probe is designed for easy interchange of TEBs (Target Emulation Board). See Table 28.

## In-circuit Debugging Kit

#### **Table 28. STMicroelectronics Development Tools**

Two configurations are available from ST:

- STXF521-IND/USB: Low-cost In-Circuit Debugging kit from Softec Microsystems. Includes STX-InDART/USB board (USB port) and a specific demo board for ST72521 (TQFP64)
- STxF-INDART

## **Flash Programming tools**

- ST7-STICK ST7 In-circuit Communication Kit, a complete software/hardware package for programming ST7 Flash devices. It connects to a host PC parallel port and to the target board or socket board via ST7 ICC connector.
- ICC Socket Boards provide an easy to use and flexible means of programming ST7 Flash devices. They can be connected to any tool that supports the ST7 ICC interface, such as ST7 EMU3, ST7-DVP3, inDART, ST7-STICK, or many third-party development tools.

## **Evaluation board**

ST7232x-EVAL with ICC connector for programming capability. Provides direct connection to ST7-DVP3 emulator. Supplied with daughter boards (core module) for ST72F321, ST72F324 & ST72F521 (the ST72F321 & ST72F324 chips are not included)

		Programming				
Supported	ST7 DVP	3 Series	ST7 EMU	ICC Socket Board		
Products	Emulator Connection kit		Emulator			Active Probe & T.E.B.
ST72324BJ, ST72F324J, ST72F324BJ	ST7MDT20-DVP3	ST7MDT20-T44/ DVP	ST7MDT20J-		ST7SB20J/xx <sup>1</sup>	
ST72324BK, ST72F324K, ST72F324BK	ST7MDT20-DVP3	ST7MDT20-T32/ DVP	EMU3	ST/MD1203-TEB		

Note 1: Add suffix /EU, /UK, /US for the power supply of your region.